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Product Change Notification - KSRA-200SOQ751 (Printer Friendly)

Date:

19 Feb 2018

Product Category:

Memory; Power Management - PWM Controllers; Sigma - Delta A/D Converters; Digital Potentiometers; System D/A Converters; Instrumentation Amplifier; Battery Management and Fuel Gauges - Battery Chargers; Temperature Sensors; 8-bit PIC Microcontrollers

Notification subject:

CCB 3041 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond in selected products of the 160K wafer technology available in 8L DFN package at NSEB assembly site

Notification text:

PCN Status:

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond in selected products of the 160K wafer technology available in 8L DFN package at NSEB assembly site

Pre Change:

Using gold (Au) bond wire, 8200T or 8600 die attach material, G770HCD or G700LTD molding compound material and C194 or EFTEC-64T lead frame material

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire 8600 die attach material, G700LTD molding compound material and C194 lead frame material

Pre and Post Change Summary:

		Post Change				
Assembly Site	UTAC Th	ai Limited LT	UTAC Thai Limited LTD. (NSEB)			
Wire material		CuPdAu Wire				
Die attach material	8200T	8600	8600	8600		
Molding compound material	G770HCD	G700LTD	G700LTD	G700LTD		
Lead frame material	C194	C194	EFTEC-64T	C194		

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying CuPdAu bond wire at NSEB assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date:

March 19, 2018 (date code: 1812)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts

Time Table Summary:

	A	August 2017			>	February 2018			March 2018						
Workweek	31	32	33	34	35		05	06	07	08	09	10	11	12	13
Initial PCN Issue Date	Χ														
Qual Report Availability										X					
Final PCN Issue Date										Х					
Estimated Implementation														Χ	



Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report

Revision History:

August 05, 2017: Issued initial notification.

August 31. 2017: Re-issued initial notification to include CCB 3073.

Februarv 19. 2018: Issued final notification. Attached the Oualification Report. Update subject to remove CCB 3073. Revised the affected parts list. Provided estimated first ship date on March 19, 2018.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_KSRA-20OSOQ751_Affected CPN.pdf PCN_KSRA-20OSOQ751_Qual Report.pdf PCN_KSRA-20OSOQ751_Affected CPN.xlsx

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